

PMP9742 REV B Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
!PCB1	1		PMP9742	Any	Printed Circuit Board	
C1	1	0.047uF	ECQ-E6473KF	Panasonic Electronic Compon	CAP FILM 0.047UF 630VDC RADIAL	Radial 12.5x5.5x11
C2	1	1uF	C1005X5R0J105M	TDK	CAP, CERM, 1uF, 6.3V, +/-20%, X5R, 0402	0402
C3	1	2.2uF	GRM21BR71E225KA73L	MuRata	CAP, CERM, 2.2uF, 25V, +/-10%, X7R, 0805	0805
C100	1	39uF	6.3ZL39MEFC4X7	Rubycon	CAP, AL, 39uF, 6.3V, +/-20%, TH	5.0x7.0mm
D1	1	68V	BZX84C68LT1G	ON Semiconductor	Diode, Zener, 68V, 225mW, SOT-23	SOT-23
D2	1	1.15V	RH06-T	Diodes Inc.	Diode, Switching-Bridge, 600V, 0.5A, MiniDIP	MiniDIP
D3	1	600V	CGRM4005-G	Comchip Technology	Diode, P-N, 600V, 1A, 3.9x1.7x1.8mm	3.9x1.7x1.8mm
D4	1	0.85V	SS110-TP	Micro Commercial Componen	Diode, Schottky, 100V, 1A, SMA	SMA
D5	1	200V	RF071M2S	Rohm	Diode, Ultrafast, 200V, 1A, SOD-123	SOD-123
R1	1	100	RG2012P-101-B-T5	Susumu Co Ltd	RES, 100 ohm, 0.1%, 0.125W, 0805	0805
R2	1	20.0	CRCW040220R0FKED	Vishay-Dale	RES, 20.0 ohm, 1%, 0.063W, 0402	0402
R4	1	100k	CRCW0402100KFKED	Vishay-Dale	RES, 100k ohm, 1%, 0.063W, 0402	0402
R5	1	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0k ohm, 1%, 0.063W, 0402	0402
R6	1	80.6k	CRCW040280K6FKED	Vishay-Dale	RES, 80.6k ohm, 1%, 0.063W, 0402	0402
R7	1	40.2k	CRCW040240K2FKED	Vishay-Dale	RES, 40.2k ohm, 1%, 0.063W, 0402	0402
RF1	1	20k	PR02000202002JR500	Vishay-Bccomponents	RES, 20k ohm, 5%, 2W, TH	Axial resistor
T1	1	4mH	750314848	Würth Elektronik eiSos	Transformer, 4mH, SMT	9.78x10.52x9.14mm
TP1, TP2	2	White	5002	Keystone	Test Point, TH, Miniature, White	Keystone5002
TP3	1	Red	5000	Keystone	Test Point, TH, Miniature, Red	Keystone5000
TP4	1	Black	5001	Keystone	Test Point, TH, Miniature, Black	Keystone5001
U1	1		UCC28910D	Texas Instruments	LOW STAND-BY POWER, CV / CC PWM HV SWITCHER WITH PRIMARY SIDE REGULATION, D0007A	D0007A

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